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pad, and the first element surface being disposed in an opposite relation with respect to the first board surface;

a conductive connecting member disposed between the board wiring pad and the element wiring pad, and

a sealing member having a sealing portion, the sealing member only making contact with the first board surface over a contact area on the first board surface completely outside of a space formed between the first board surface and the first element surface with the sealing member being formed from a hot-melt material having a characteristic preventing the hot-melt material from spreading from the contact area into the space.

D 2
168. (Thrice Amended) A surface acoustic wave device, comprising:

a printed circuit board of a material possessing a first region and a second region which is thicker than the first region, the second region including a board wiring pad thereon; a surface acoustic wave element possessing a first element surface and a second element surface, the first element surface including a transducer portion, a element wiring pad and a surface acoustic wave absorbing member, and being disposed with a face-down so that the surface acoustic wave absorbing member is disposed in an opposite relation with respect to the first region of the printed circuit board;

a conductive connecting member disposed between the board wiring pad and the element wiring pad, and

a sealing member having a sealing portion, the sealing member only making contact with the first board surface over a contact area on the first board surface completely outside of a space formed between the first board surface and the first element surface with the sealing member being formed from a hot-melt material having a characteristic preventing the hot-melt material from spreading from the contact area into the space.

D3

170. (Thrice Amended) A surface acoustic wave device, comprising:

a printed circuit board including a first board surface and a second board surface, the first board surface having a board wiring pattern;

a surface acoustic wave element possessing a first element surface and a second element surface, the first element surface including a transducer portion, a element wiring pad and a surface acoustic wave absorbing member, and the first element surface being disposed in an opposite relation with respect to the first board surface;

a conductive connecting member disposed between the board wiring pattern and the element wiring pad, the conductive connecting member being composed of a plurality of bumps stacked according to a spacing between the board wiring pattern and the element wiring pad, and

a sealing member having a sealing portion, the sealing member only making contact with the first board surface over a contact area on the first board surface completely outside of a space formed between the first board surface and the first element surface with the sealing member being formed from a hot-melt material having a characteristic preventing the hot-melt material from spreading from the contact area into the space.

REMARKS

Favorable reconsideration of this application as presently amended and in light of the following discussion is respectfully requested.

Claims 166-171 are presently active in this application. Claims 166, 168, and 170 have been amended to better clarify the present invention without the introduction of any new matter.